

# TA8053H

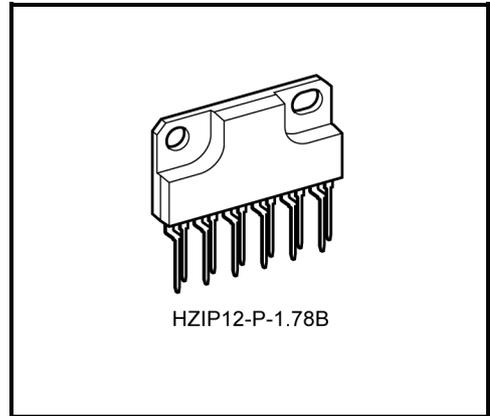
## 3A DC MOTOR DRIVER WITH DIAGNOSIS

The TA8053H is a bidirectional DC motor driver with a current capacity of 3A. Inputs DI1 and DI2 are combined to select one of forward, reverse, stop, and brake modes.

The inputs are TTL-compatible, and separate power supplies are provided for the logic and output sections. The IC also incorporates various protective functions as well as a self-diagnostic function for diagnostic output

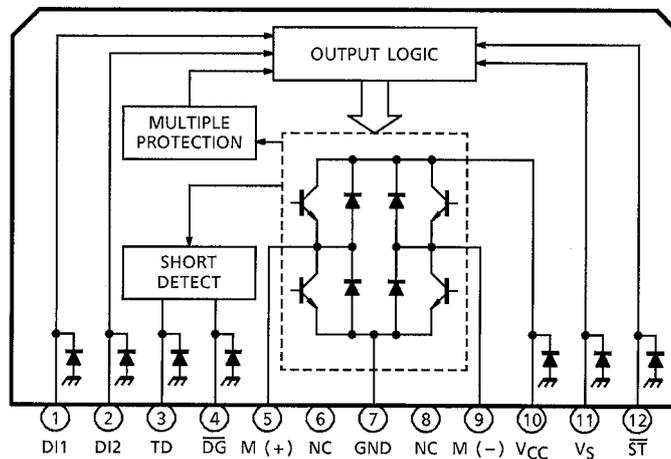
### FEATURES

- Output current capacity : 3A (Max.)
- Small standby current consumption : 100μA (Max.)
- Four operation modes : Forward, reverse, stop, and brake
- Multiple protective functions : Short-circuit protection, thermal shutdown, and over-voltage shutdown
- Self-diagnostic output : On short-circuit detection
- Built-in counter electromotive force absorption diodes.
- Plastic package HZIP-12pin



Weight: 4.0 g (Typ.)

### BLOCK DIAGRAM AND PIN LAYOUT



## PIN DESCRIPTION

PIN No.	SYMBOL	DESCRIPTION
1 2	DI1 DI2	Output status control pin. Connects to a PNP-type voltage comparator.
3	TD	Delays the $\overline{DG}$ output. A capacitor is placed between this pin and GND. When the pin is open, $\overline{DG}$ is in switching state.
4	$\overline{DG}$	Self-diagnostic output pin. When the output current increases above 6A (typically), a switching waveform is output from this pin as from M (+) and M (-). If a capacitor is connected to the TD pin, the signal from this pin will go low after a certain delay. The output is an open-collector output. The delay time is approximately calculated by the following formula : $T_D (ms) = 50 \times C_T (\mu F)$ Permissible $C_T$ range : 0.01 $\mu F$ to 2 $\mu F$
5	M (+)	Connects to the DC motor. Both the sink and the source have a current capacity of 3A. Diodes for absorbing counter electromotive force are contained on the $V_{CC}$ and GND sides.
7	GND	Grounded
9	M (-)	Connects to the DC motor together with pin 5 and has the same function as pin 5. This pin is controlled by the inputs from pins 1 and 2.
10	$V_{CC}$	Power supply pin for the output section
11	$V_S$	Power supply pin for the control section. This pin is completely separated from the $V_{CC}$ pin.
12	$\overline{ST}$	When this pin is opened or grounded, the output turns off to reduce the current consumption below 100 $\mu A$ . If standby mode is not needed, the pin is connected to $V_{CC}$ .
6, 8	NC	Not connected. (Electrically, this pin is completely open.)

## TRUTH TABLE

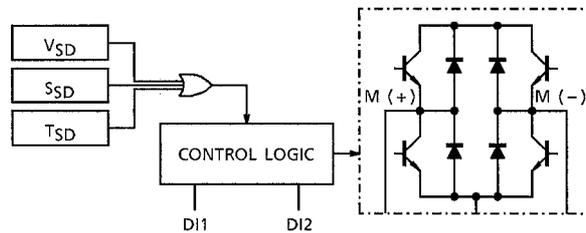
INPUT		OUTPUT			OUTPUT MODE
DI1	DI2	$\overline{ST}$	M (+)	M (-)	
H	H	H	L	L	BRAKE
L	H	H	L	H	REVERSE
H	L	H	H	L	FORWARD
L	L	H	OFF (high impedance)		STOP
H / L	H / L	L	OFF (high impedance)		STANDBY

## DESCRIPTION OF MULTI-PROTECTIVE OPERATION

The TA8053H has functions for protection from over-voltage (VSD), over-current (ISD), and overheat (TSD). These functions protect the IC (and the motor load in some cases) from deterioration or destruction due to power-related overstress.

The three functions work independently.

Each function is explained below.



### 1. Overvoltage protection (Vsd)

- Basic operation

When the voltage supplied to the VCC pin is up to the VSD detection voltage, the output is controlled by the input signals. However, when the VCC voltage exceeds the detection voltage, the output enters high-impedance state regardless of the input signals.

- Detailed explanation

The VSD voltage is detected by comparing the reference voltage which is constructed by zener diode. When the center voltage of the resistor is higher than the Zener voltage, a transistor-off instruction is issued to the control logic. When it is lower than the Zener voltage, the logic is controlled by the input signals from pins 1 and 2.

### 2. Overheat protection (Tsd)

- Basic operation

When the junction (chip) temperature is up to the TSD detection temperature, the output is controlled by the input signals. When it exceeds the TSD detection temperature, the output enters high-impedance state regardless of the input signals.

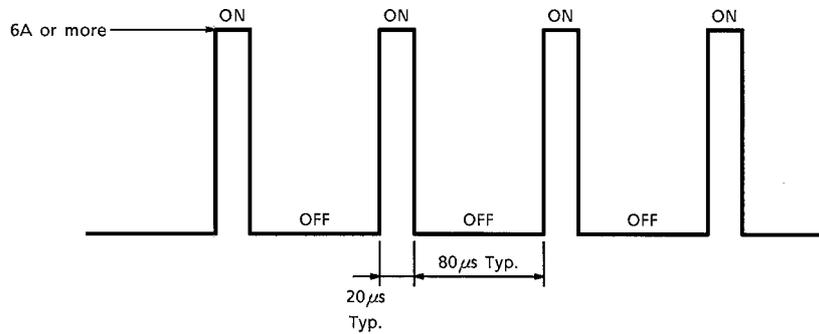
- Detailed explanation

The temperature is detected by monitoring VBE of a transistor on the chip. When the transistor VBE is lower than the internal reference voltage, an output transistor-off instruction is issued to the control logic. When it is higher than the internal reference voltage, the logic is controlled by the input signals from pins 1 and 2.

**3. Overcurrent protections (I<sub>SD</sub>)**

- Basic operation

When the output current (pin 5 or 9, I sink or I source) is up to the I<sub>SD</sub> detection current, the output is controlled by the input signals. When it exceeds the detection current, the output assumes a switching waveform as shown in Fig.1.



**Fig.1 Basic Operation**

- Detailed explanation

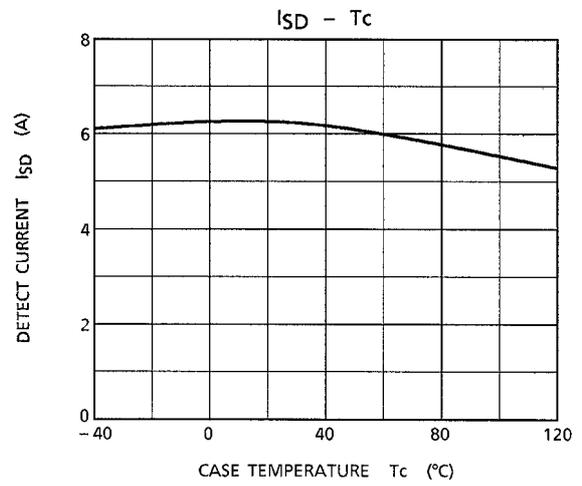
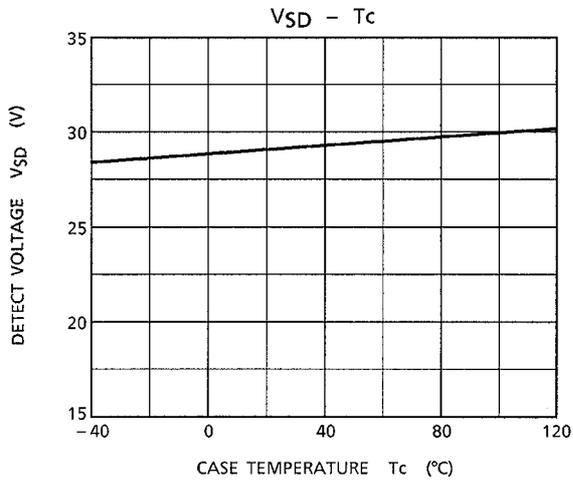
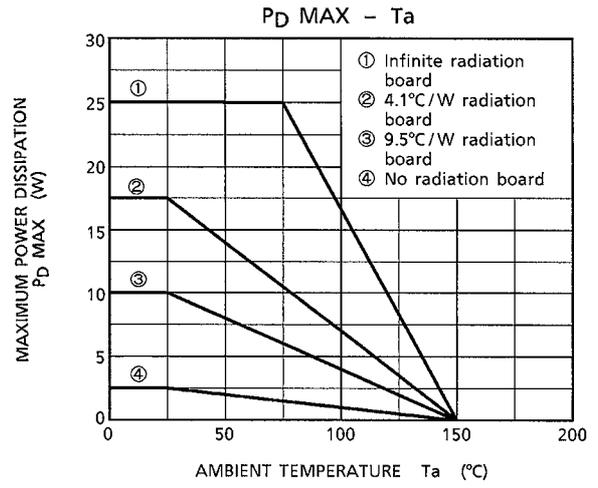
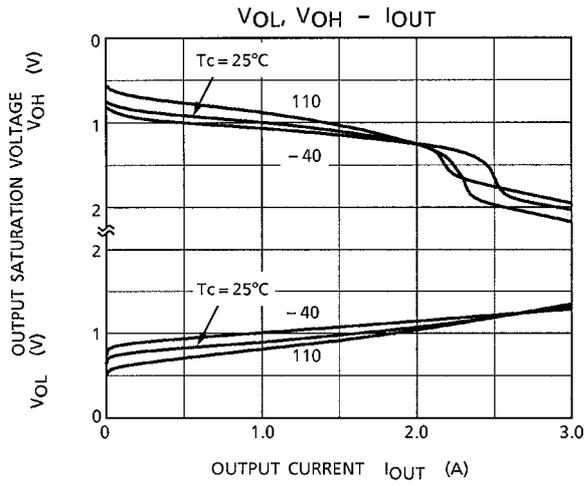
The output current is detected by monitoring the V<sub>BE</sub> from each output transistor. One detection circuit connects to one of the output transistors and leads to the short-circuit protection circuit. When a current exceeding the I<sub>SD</sub> detection current flows through one of the four output transistors, the short-circuit protection circuit is activated. This circuit contains a timer. When over-current condition continues for 20μs (typically), the protection circuit places the output in high-impedance mode and, 80μs (typically) later, returns the IC to ON mode. The switching-waveform output is repeated until over-current condition is no longer present.

**MAXIMUM RATINGS (Ta = 25°C)**

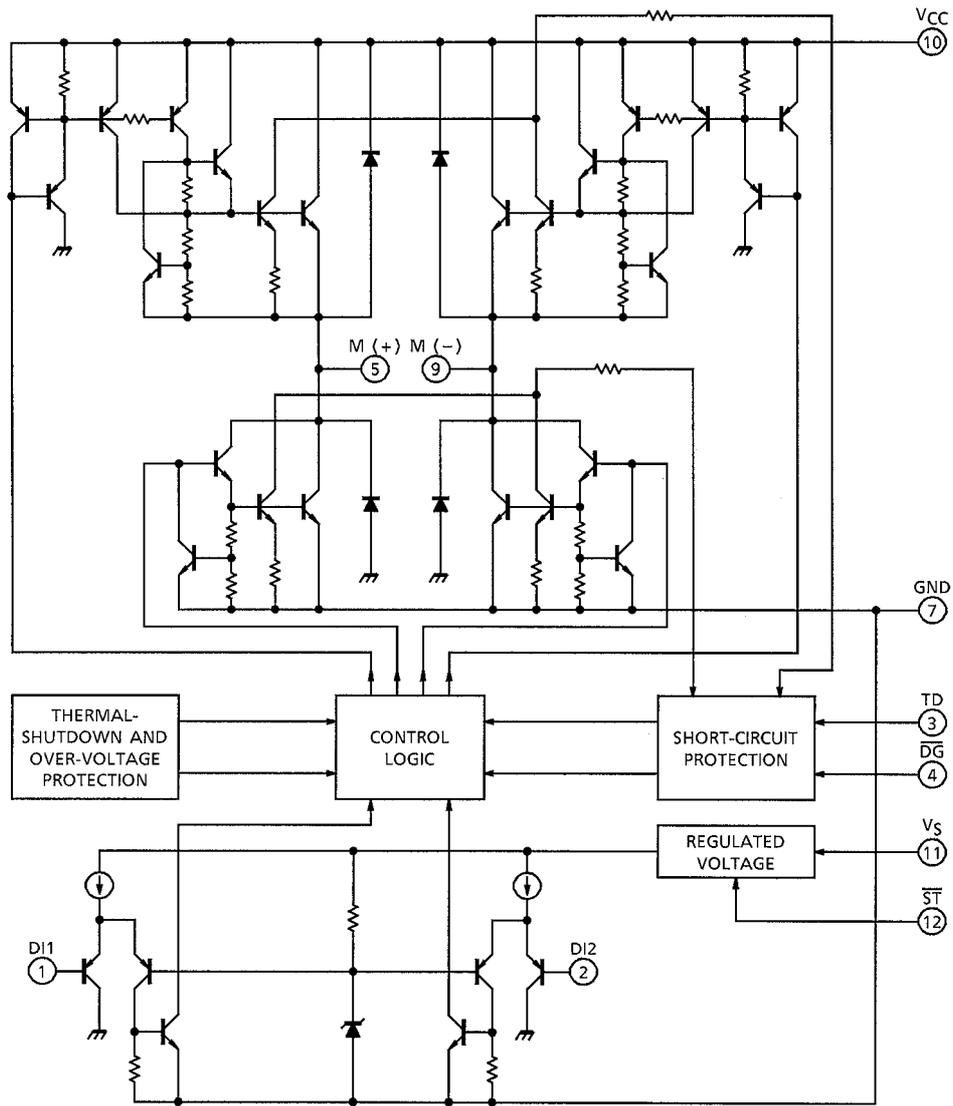
CHARACTERISTIC	SYMBOL	RATING	UNIT
Power Supply Voltage	V <sub>CC</sub>	30	V
	V <sub>CC</sub>	60 (1s)	
Input Voltage	V <sub>IN</sub>	-0.3~V <sub>CC</sub>	V
Output Current	I <sub>O AVE</sub>	3.0	A
Operation Temperature	T <sub>opr</sub>	-40~110	°C
Storage Temperature	T <sub>stg</sub>	-55~150	°C
Power Dissipation	P <sub>D</sub>	25	W
Lead Temperature Time	T <sub>sol</sub>	260 (10s)	°C

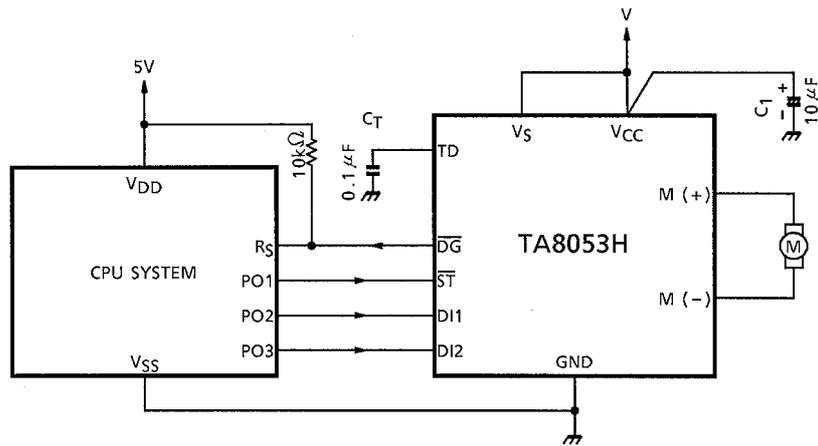
## ELECTRICAL CHARACTERISTICS ( $V_{CC} = 6\sim 16V$ , $T_c = -40\sim 110^\circ C$ )

CHARACTERISTIC	SYMBOL	PIN	TEST CIRCUIT	TEST CONDITION	MIN	TYP.	MAX	UNIT
Current Consumption (I)	$I_{S1}$	$V_S$	—	Stop	—	8	14	mA
	$I_{S2}$		—	Forward / Reverse	—	22	42	
	$I_{S3}$		—	Brake	—	22	42	
Current Consumption (II)	$I_{CC1}$	$V_{CC}$	—	Stop	—	5	8	mA
	$I_{CC2}$		—	Forward / Reverse	—	18	42	
	$I_{CC3}$		—	Brake	—	5	8	
Input Voltage	$V_{IL}$	DI1 / DI2	—	—	—	—	0.8	V
	$V_{IH}$		—	—	2.0	—	—	
Input Current	$I_{IL}$	DI1 / DI2	—	$V_{IN} = 0.4$	—	—	-50	$\mu A$
	$I_{IH}$		—	$V_{IN} = V_{CC}$	—	—	10	
Input Voltage	$V_{IL}$	$\overline{ST}$	—	—	—	—	0.8	V
	$V_{IH}$		—	—	2.0	—	—	
Input Current	$I_{IL}$	$\overline{ST}$	—	$V_{IN} = 0.4$	—	—	50	$\mu A$
	$I_{IH}$		—	$V_{IN} = V_{CC}$	—	—	4	
Output Saturation Voltage	$V_{sat} \text{ (total)}$	M (+) / M (-)	—	$I_O = 1.5A$	1.0	2.1	2.8	V
			—	$I_O = 3.0A$	2.0	3.3	4.1	
Output Leakage Current	$I_{LEAK-U}$	M (+) / M (-)	—	$V_O = 0V$	—	—	-100	$\mu A$
	$I_{LEAK-L}$		—	$V_O = V_{CC}$	—	—	100	
Output Voltage	$V_{OL}$	$\overline{DG}$	—	$I_{OL} = 3mA$	—	—	0.5	V
Output Leakage Current	$I_{LEAK-L}$		—	$V_{OUT} = V_{CC}$	—	—	10	$\mu A$
Diode Forward Voltage	$V_{F-U}$	M (+) / M (-)	—	$I_F = 3.0A$	—	5.0	—	V
	$V_{F-L}$		—	$I_F = 3.0A$	—	1.5	—	
Overcurrent Detection	$I_{SD}$	—	—	—	4.2	6	8	A
Shutdown Temperature	$T_{SD}$	—	—	—	—	150	—	$^\circ C$
Overvoltage Detection	$V_{SD}$	—	—	—	26	29	32	V
Standby Current	$I_S$	$V_{CC}+V_S$	—	$\overline{ST} = GND$	—	—	100	$\mu A$
Thermal Resistance	$R\theta_{j-c}$	—	—	—	—	3	—	$^\circ C / W$
Transfer Delay Time	$t_{pLH}$	—	—	—	—	1	10	$\mu s$
	$t_{pHL}$	—	—	—	—	1	10	



**I / O EQUIVALENT CIRCUIT**



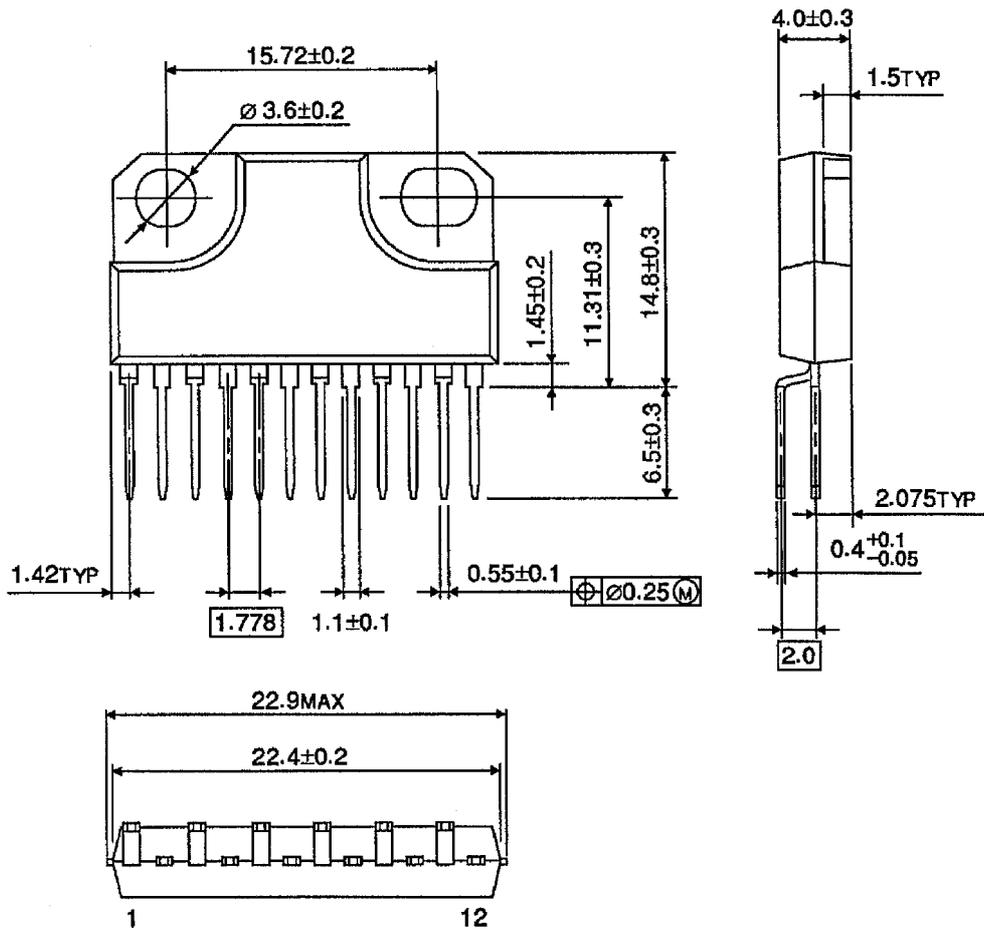
**EXAMPLE OF APPLICATION CIRCUIT**

- (\*): Cautions for wiring  
C<sub>1</sub> is for absorbing disturbance noise, etc.  
So, connect it as close as possible.

## Package Dimensions

HZIP12-P- 1.78B

Unit: mm



Weight: 4.0 g (Typ.)

**RESTRICTIONS ON PRODUCT USE**

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